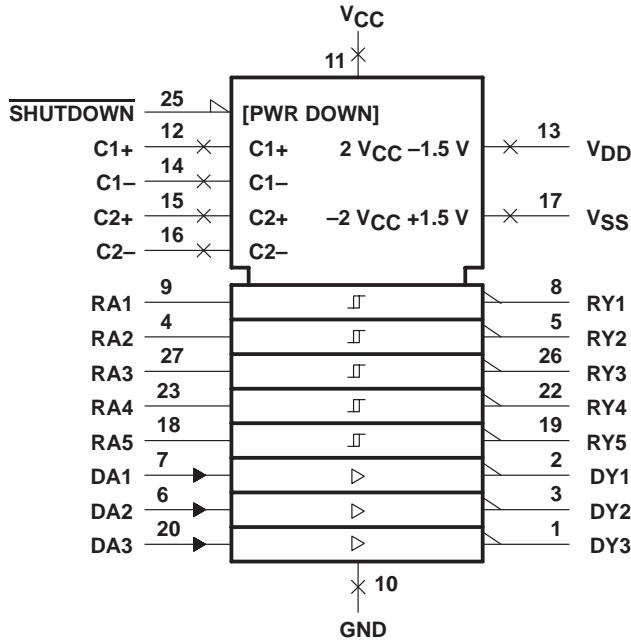




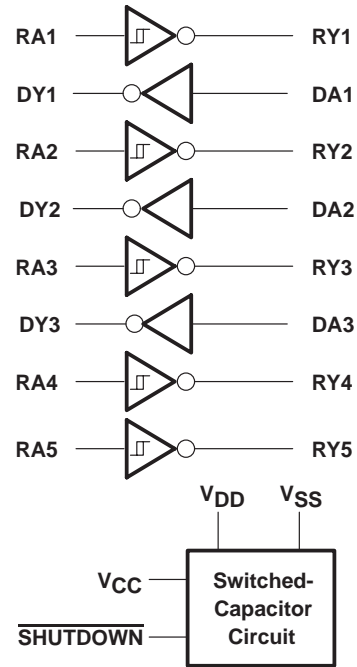
# SN75LBC187 MULTICHANNEL EIA-232 DRIVER/RECEIVER WITH CHARGE PUMP

SLLS130C – SEPTEMBER 1991 – REVISED MAY 1995

## logic symbol†



## logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub> (see Note 1)	0.3 V to 6 V
Positive output supply voltage range, V <sub>DD</sub>	V <sub>CC</sub> - 0.3 V to 15 V
Negative output supply voltage range, V <sub>SS</sub>	0.3 V to -15 V
Input voltage range, V <sub>I</sub> : RA	±30 V
All other inputs	-0.3 V to V <sub>CC</sub> + 3 V
Output voltage range, V <sub>O</sub> : DY	-2 V <sub>CC</sub> + 1.2 V to 2 V <sub>CC</sub> - 1.2 V
All other outputs	-0.3 V to V <sub>CC</sub> + 3 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to the network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
DB	1025 mW	8.2 mW/°C	656 mW

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**recommended operating conditions**

		MIN	NOM	MAX	UNIT	
Supply voltage, $V_{CC}$		4.5	5	5.5	V	
High-level input voltage, $V_{IH}$	DA	2			V	
	RA, <u>SHUTDOWN</u>	2.4				
Low-level input voltage, $V_{IL}$	RA, DA, <u>SHUTDOWN</u>	0.8			V	
Receiver input voltage, $V_I$		-25			25	V
High-level output current, $I_{OH}$	RY				-1	mA
Low-level output current, $I_{OL}$	RY				3.2	mA
Output current, $I_O$	$V_{DD}$				$\pm 10$	$\mu A$
	$V_{SS}$				$\pm 10$	$\mu A$
C1, C2, C3, C4 charge pump capacitors		0.1	0.47			$\mu F$
Operating free-air temperature, $T_A$		0			70	$^{\circ}C$

**electrical characteristics over recommended operating conditions (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
$V_{OH}$	High-level output voltage	Receiver	$I_O = -1$ mA	3.5			V	
		Driver	$R_L = 3$ k $\Omega$ to GND	5	7			
$V_{OL}$	Low-level output voltage	Receiver	$I_O = 3.2$ mA	0.4			V	
		Driver	$R_L = 3$ k $\Omega$ to GND	-7		-5		
$V_{IT+}$	Receiver positive-going input voltage threshold			1.7		2.4	V	
$V_{IT-}$	Receiver negative-going input voltage threshold			0.8	1.2		V	
$V_{hys}$	Receiver input hysteresis voltage ( $V_{IT+} - V_{IT-}$ )			0.5		1	V	
$r_i$	Receiver input resistance	$V_{CC} = 5$ V, $T_A = 25^{\circ}C$		3	5	7	k $\Omega$	
$r_o$	Driver output resistance	$V_{CC} = 0$ , $V_O = \pm 2$ V		300			$\Omega$	
$I_I$	Input current (DA, <u>SHUTDOWN</u> )	$V_I = 0$ to $V_{CC}$					$\pm 50$	$\mu A$
$I_{OS}$	Driver output short-circuit current	$V_O = 0$		$\pm 10$			mA	
$I_{CC}$	Supply current	Normal operation	All outputs open, <u>SHUTDOWN</u> at 2.4 V	15		30	mA	
		Shutdown mode	All outputs open, <u>SHUTDOWN</u> at 0.1 V	10			$\mu A$	

† All typical values are at  $V_{CC} = 5$  V and  $T_A = 25^{\circ}C$ .

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**switching characteristics over recommended operating conditions,  $T_A = 25^\circ\text{C}$  (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low- to high-level output	Receiver	R <sub>L</sub> = 5 kΩ, See Figure 1	C <sub>L</sub> = 50 pF,	1.25	μs
		Driver	R <sub>L</sub> = 3 kΩ, See Figure 2	C <sub>L</sub> = 1200 pF,	1.25	μs
t <sub>PHL</sub>	Propagation delay time, high- to low-level output	Receiver	R <sub>L</sub> = 5 kΩ, See Figure 1	C <sub>L</sub> = 50 pF,	1.25	μs
		Driver	R <sub>L</sub> = 3 kΩ, See Figure 2	C <sub>L</sub> = 1200 pF,	1.25	μs
t <sub>r</sub>	Rise time, driver output		R <sub>L</sub> = 3 kΩ, V <sub>O</sub> = -3 V to 3 V,	C <sub>L</sub> = 50 pF, See Note 2	200	ns
			R <sub>L</sub> = 3 kΩ, V <sub>O</sub> = -3.3 V to 3.3 V,	C <sub>L</sub> = 2500 pF, See Note 3	1.5	μs
t <sub>f</sub>	Fall time, driver output		R <sub>L</sub> = 3 kΩ, V <sub>O</sub> = 3 V to -3 V	C <sub>L</sub> = 50 pF,	200	ns
			R <sub>L</sub> = 3 kΩ, V <sub>O</sub> = 3.3 V to -3.3 V	C <sub>L</sub> = 2500 pF,	1.5	μs

- NOTES: 2. The 200 ns for the output to change from -3 V to 3 V (or vice versa) corresponds to the 30 V/μs maximum slew rate of EIA/TIA-232-E, EIA/TIA-562, and ITU Recommendation V.28.
3. The more stringent requirement for transition times comes from the EIA/TIA-562, which requires the rise and fall times to be measured from 3.3 V.



PARAMETER MEASUREMENT INFORMATION

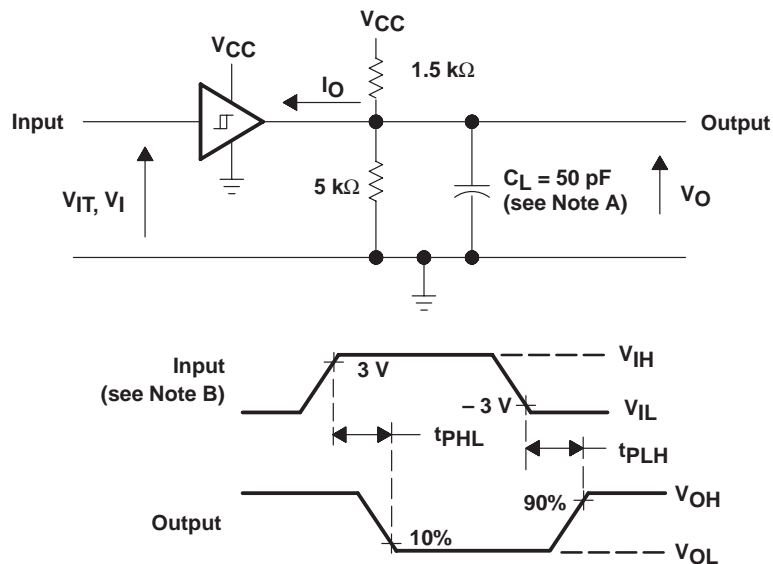
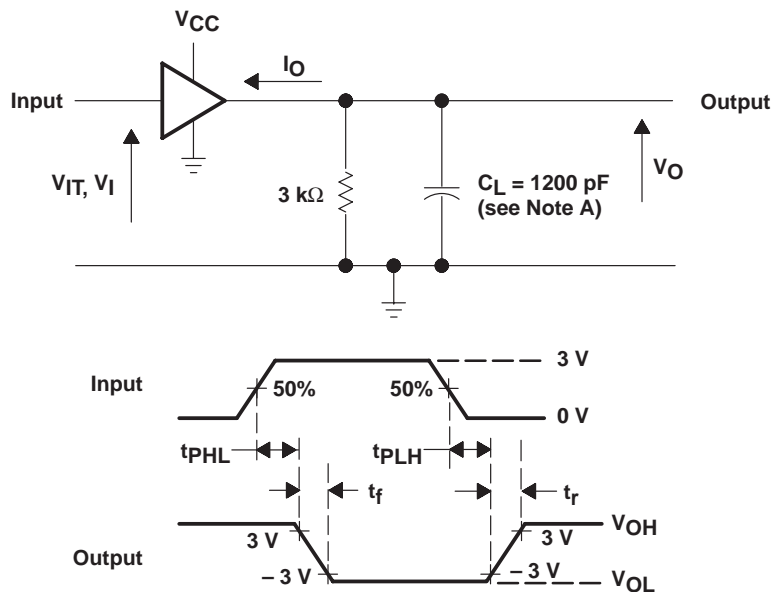


Figure 1. Receiver Test Circuit and Waveforms



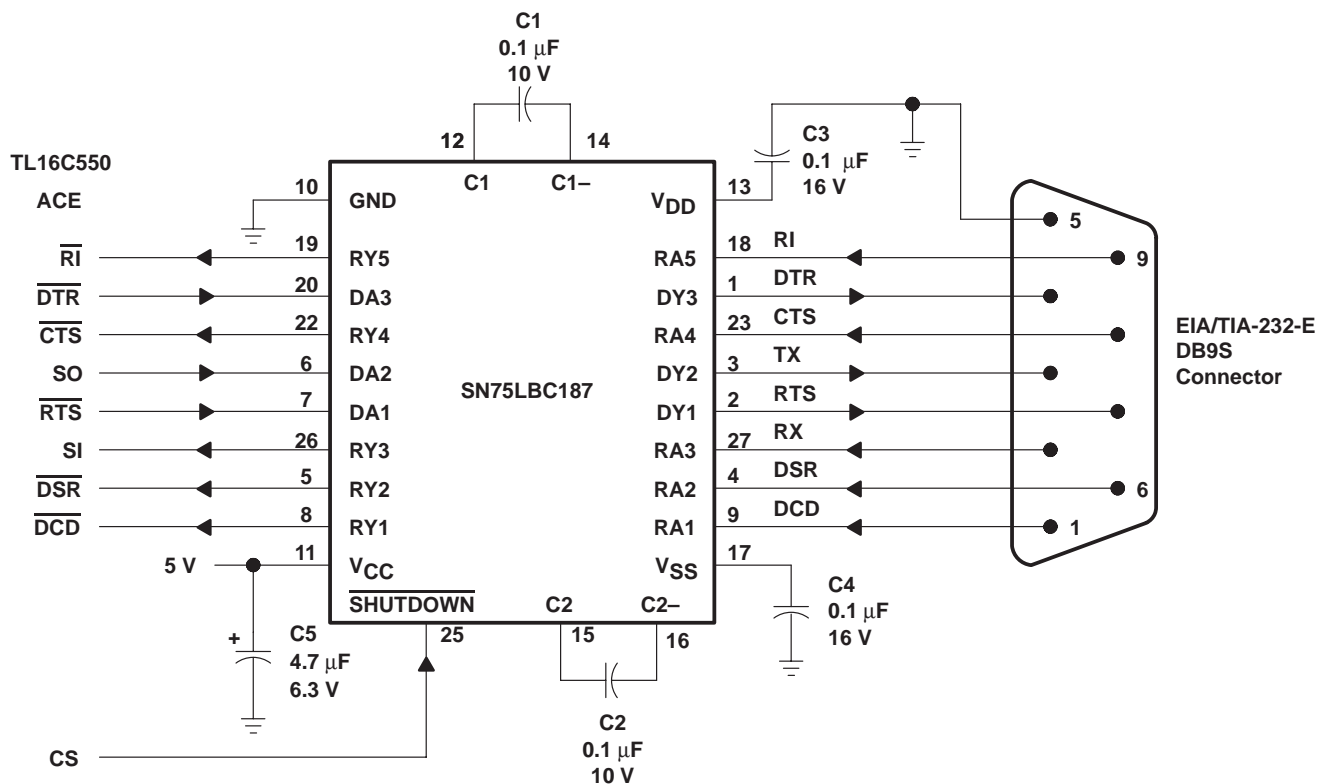
- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. The pulse generator has the following characteristics:  $t_w = 8.33\text{ }\mu\text{s}$ ,  $\text{PRR} = 60\text{ kHz}$ ,  $t_r = t_f \leq 50\text{ ns}$ .

Figure 2. Driver Test Circuit and Waveforms

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## APPLICATION INFORMATION



NOTE: C1, C2, C3, and C4 are Z5U-type ceramic-chip capacitors.

Figure 3. Typical SN75LBC187 Connection

**SN75LBC187**  
**MULTICHANNEL EIA-232 DRIVER/RECEIVER**  
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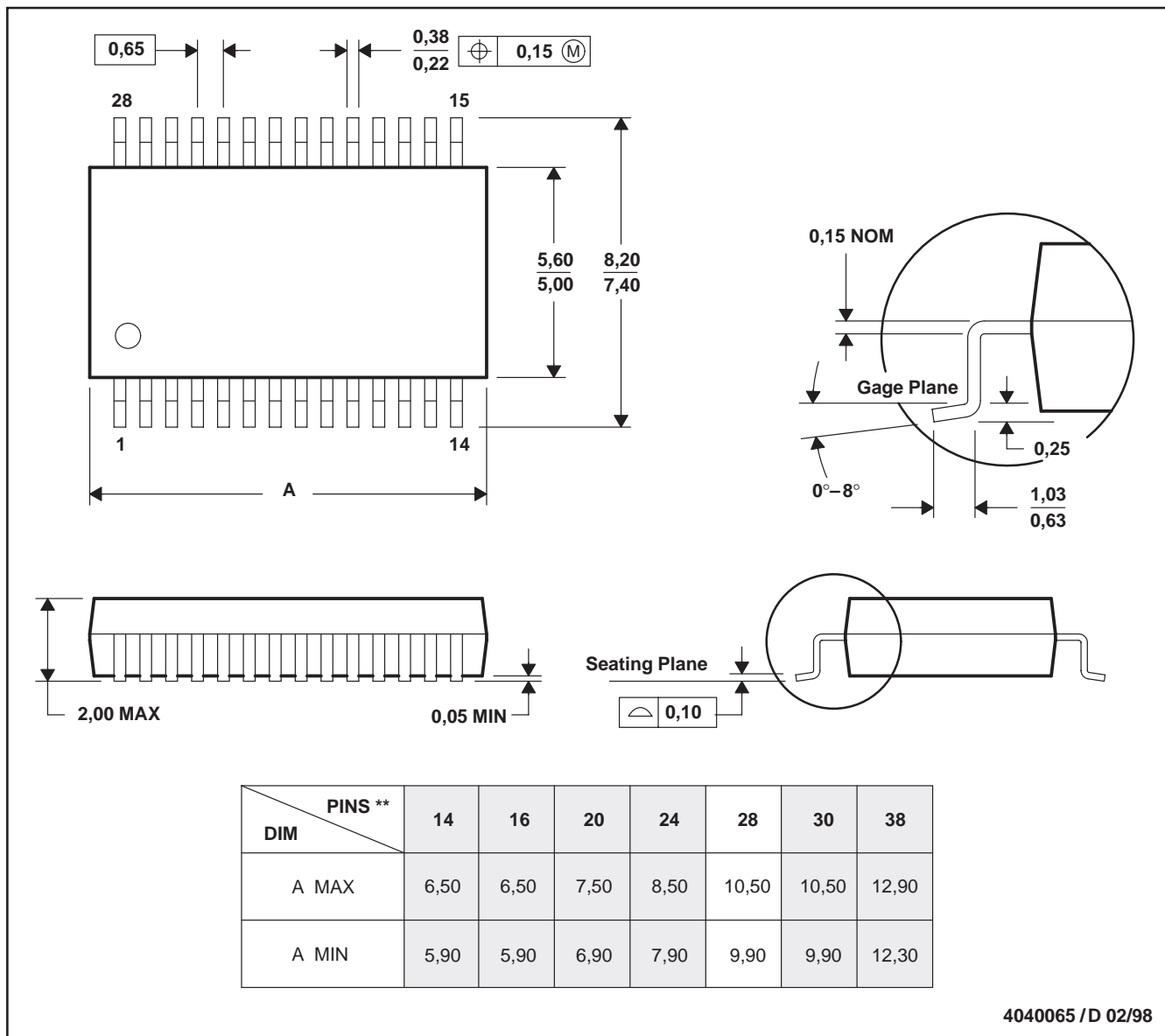
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**MECHANICAL DATA**

**DB (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

28 PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75LBC187DBR	ACTIVE	SSOP	DB	28	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC187	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75LBC187DBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75LBC187DBR	SSOP	DB	28	2000	356.0	356.0	35.0

# DB0028A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214853/B 03/2018

### NOTES:

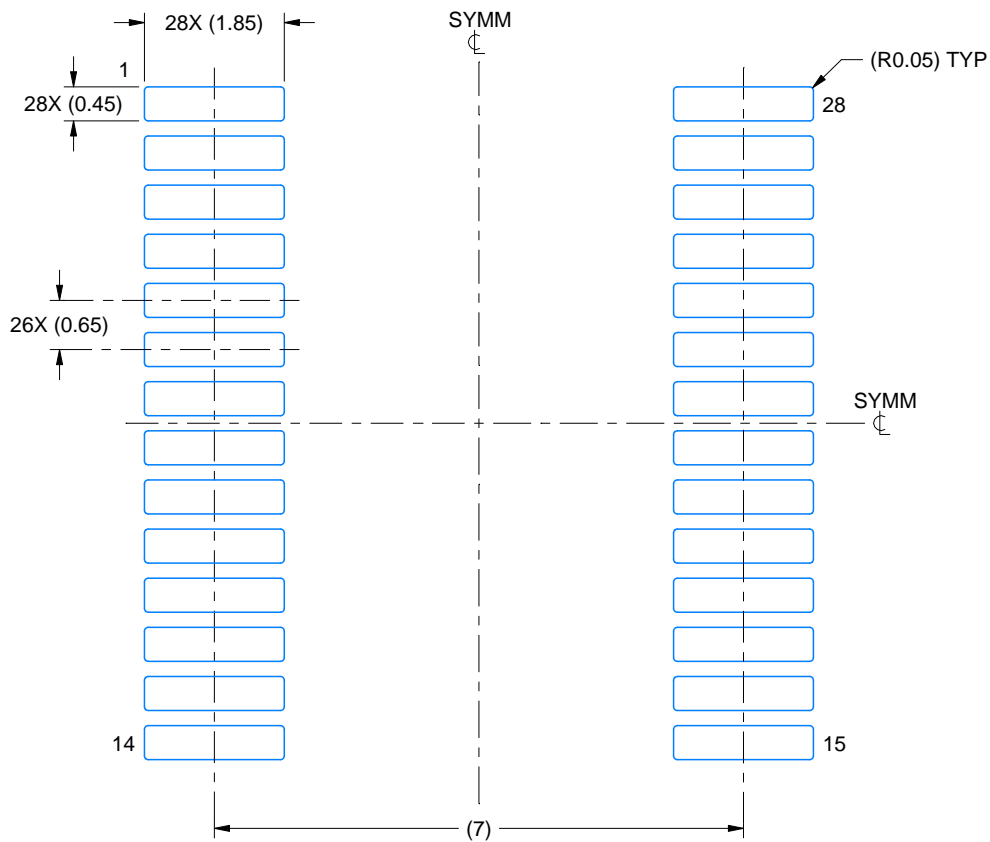
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4214853/B 03/2018

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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